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10124632-0211G03LF
10124632-0211G03LF : Vertical Through-Hole 288 Position
DDR4 DIMM Connector, 0.85mm PITCH



Customer drawing

Product Environmental Compliance Report

Specifications

Download document

ACTIVE

RoHS Compliant

Distributor Stock

Print Datasheet

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Contact our sales/technical support
Sample request

General Dimensional Electrical Mechanical Physical Approvals / Certifications Mounting Other Features	
General	
Number of contacts (Total)	288
Product Type	DDR4
Memory Key Side	right
Insertion Style	Direct
Mating half	The mated module meets JEDEC Specification MO-309
Number of ejectors	2
Number of slots	1
Series Number	10124632
Dimensional	
Height (Above board)	21.3 mm (0.839 in.)
Length (Tail)	3.20 mm (0.126 in.)
Spacing (Center line)	0.85 mm (0.0335 in.)
Electrical	
Withstanding Voltage	500V AC rms
Current rating	0.75A @ 30°C
Resistance (Contact)	10 milli ohms
Resistance (Insulation)	1 M-ohms min.
Voltage rating	1.2 V
Mechanical	
Durability (Mating cycles)	25 Mating Cycles
Retention force (Contact)	2.94N (300g)
Physical	
Color (Ejector)	Green
Color (Housing)	Black
Material (Contact)	Copper Alloy
Material (Housing)	Thermoplastic (UL 94 V-O)
Plating (Contact area)	0.76 µm (30 µin.) Gold
Plating (Tail)	2.54 µm (100 µin.) Tin
Underplating (Contact)	1.27 µm (50 µin.) Nickel
Hold Down	Forklock
Operating Voltage	1.2V
Plating (Hold-down)	2.00 µm (80 µin.) Tin
Temperature (Operating - continuous)	+65°C
Temperature (Range)	-55°C to +65°C
Approvals / Certifications	
Approvals / Certifications	In Process
Standards	JEDEC MO-309
Mounting	
Alignment pegs	No
Mounting style	Board Through - Mount
Retention feature (Board)	Yes
Solder process	Wave
Other Features	
Packaging (Type)	Soft tray
Form Factor	Standard

Disclaimer : The information above is for reference only. For more technical details, refer to product specification and application specification.